

Atty. Dkt. No. 039153-0683 (H1721)

**Amendments to the Specification:**

Please amend the specification as follows:

Please replace paragraph starting at page 1, paragraph number [0001], with the following rewritten paragraph:

[0001] The present invention is related to integrated circuit (IC) substrates or wafers and to processes of making IC substrates or wafers. More particularly, the present invention relates to a method of forming ~~strained~~ semiconductor structures on substrates and to ~~strained~~ semiconductor structures or layers.